

Title (en)  
METHOD FOR GLUING FPCB'S

Title (de)  
VERFAHREN ZUR VERKLEBUNG VON FPCB'S

Title (fr)  
PROCEDE DE COLLAGE DE CARTES DE CIRCUITS IMPRIMES FLEXIBLES

Publication  
**EP 1590416 A1 20051102 (DE)**

Application  
**EP 03782461 A 20031219**

Priority  
• EP 0314622 W 20031219  
• DE 10303518 A 20030129  
• DE 10317403 A 20030530

Abstract (en)  
[origin: WO2004067665A1] The invention relates to the gluing of plastic pieces, in particular, Flexible Printed Circuit Boards (FPCB's). According to the invention, a thermally-activated adhesive is used for the gluing, comprising (i) at least one thermoplastic polymer or a modified rubber and (ii) at least one resin, preferably comprising at least one phenol resin and at least one epoxy resin.

IPC 1-7  
**C09J 7/02**; **C08J 5/18**

IPC 8 full level  
**C09J 5/06** (2006.01); **C09J 7/10** (2018.01); **H05K 3/38** (2006.01); **C08L 21/00** (2006.01); **C08L 23/00** (2006.01); **C08L 61/00** (2006.01); **C08L 63/00** (2006.01); **C08L 67/00** (2006.01); **C08L 75/04** (2006.01); **C08L 77/00** (2006.01); **H05K 1/00** (2006.01)

CPC (source: EP KR US)  
**B29C 65/48** (2013.01 - KR); **C09J 5/00** (2013.01 - KR); **C09J 5/06** (2013.01 - EP KR US); **C09J 7/00** (2013.01 - KR); **C09J 7/10** (2017.12 - EP US); **H05K 1/0393** (2013.01 - KR); **H05K 3/386** (2013.01 - EP KR US); **C08L 21/00** (2013.01 - EP US); **C08L 23/00** (2013.01 - EP US); **C08L 61/00** (2013.01 - EP US); **C08L 63/00** (2013.01 - EP US); **C08L 67/00** (2013.01 - EP US); **C08L 75/04** (2013.01 - EP US); **C08L 77/00** (2013.01 - EP US); **C09J 2421/00** (2013.01 - EP KR US); **C09J 2423/00** (2013.01 - EP KR US); **C09J 2461/00** (2013.01 - EP KR US); **C09J 2463/00** (2013.01 - EP US); **C09J 2467/00** (2013.01 - EP KR US); **C09J 2467/006** (2013.01 - EP US); **C09J 2475/00** (2013.01 - EP US); **C09J 2477/00** (2013.01 - EP US); **C09J 2479/086** (2013.01 - EP US); **H05K 1/0393** (2013.01 - EP US); **H05K 2201/0129** (2013.01 - EP KR US); **H05K 2201/0133** (2013.01 - EP US); **H05K 2201/0209** (2013.01 - EP US); **Y10T 428/31511** (2015.04 - EP US); **Y10T 428/31721** (2015.04 - EP US); **Y10T 428/31786** (2015.04 - EP US)

Citation (search report)  
See references of WO 2004067665A1

Designated contracting state (EPC)  
DE ES FR GB IT

DOCDB simple family (publication)  
**WO 2004067665 A1 20040812**; AU 2003290101 A 20040823; EP 1590416 A1 20051102; JP 2007515496 A 20070614; KR 20050094049 A 20050926; US 2006088715 A1 20060427

DOCDB simple family (application)  
**EP 0314622 W 20031219**; AU 2003290101 A 20031219; EP 03782461 A 20031219; JP 2004567323 A 20031219; KR 20057014082 A 20050729; US 54375303 A 20031219